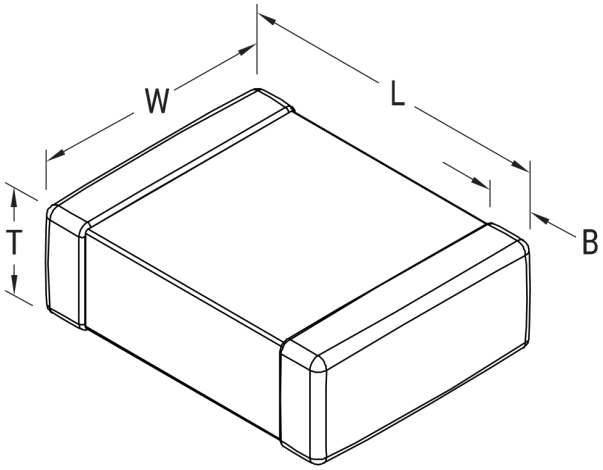
CKC33C822GEGAC7210

KC-LINK Comm C0G, Ceramic, 8200 pF, 2%, 1200 VDC, C0G, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640



Click here for the 3D model.

Dimensions	
Chip Size	3640
L	9.3mm +/-0.6mm
W	10.2mm +/-0.4mm
T	2mm +/-0.20mm
B	1.27mm +/-0.4mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	1000

General Information	
Series	KC-LINK Comm C0G
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	790 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	8200 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	2%
Voltage DC	1200 VDC
Dielectric Withstanding Voltage	1440 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms